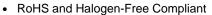
# P-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY							
V <sub>DS</sub> (V)	$R_{DS(on)}$ (m $\Omega$ )(Typ.)	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)				
- 40	30 at V <sub>GS</sub> = - 10 V	- 7	10.5 nC				
- 40	42 at V <sub>GS</sub> = - 4.5 V	- /					

#### **FEATURES**

- DT-Trench Power MOSFET
- Excellent R<sub>DSON</sub>



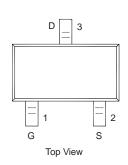


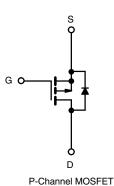
ROHS

#### **APPLICATIONS**

- Power Switching Application
- · Hard Switched and High Frequency Circuits
- DC-DC Converter







ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V <sub>DS</sub>	- 40	V		
Gate-Source Voltage	$V_{GS}$	± 20	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		
Continuous Drain Current (T, I = 150 °C) <sup>a</sup>	T <sub>C</sub> = 25 °C		- 7		
Continuous Drain Current (1) = 130 C)	T <sub>C</sub> = 100 °C	ID	- 4.8	Α	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	- 28	^	
Single Pulse Avalanche Energy		E <sub>AS</sub>	36	mJ	
Maximum Power Dissipation <sup>c</sup>	T <sub>A</sub> = 25 °C	В	1.2	W	
waxiiiiuiii Fowei Dissipalioli	T <sub>A</sub> = 100 °C	P <sub>D</sub>	0.5	] vv	
Operating Junction and Storage Temperature Range	)	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYPICAL	UNIT		
Junction-to-Ambient <sup>d</sup>	R <sub>thJA</sub>	105	°C/W		

#### Notes

- a. Calculated continuous current based on maximum allowablejunction temperature.
- b. Repetitive rating; pulse width limited by max. junction temperature.
- c. Pd is based on max. junction temperature, using junction-case thermal resistance.
- d. The value of R<sub>BJA</sub> is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper,in a still air environment with Ta=25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	•		•	•		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 40			V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \mu A$	- 1		- 3	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zoro Coto Voltago Proin Current		V <sub>DS</sub> = - 40 V, V <sub>GS</sub> = 0 V			- 1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -32 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 10	μΑ
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 7			Α
D : 0		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 3 A		30	38	mΩ
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = -3 A		42	55	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 5 V, I <sub>D</sub> = -3 A		8.5		S
Dynamic <sup>b</sup>	•			•	•	
Input Capacitance	C <sub>iss</sub>			966		pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		85.6		
Reverse Transfer Capacitance	C <sub>rss</sub>	1		75		
Total Gate Charge	$Q_g$			10.5		nC
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -3 \text{ A}$		3.2		
Gate-Drain Charge	$Q_{gd}$	1		3		
Gate Resistance	$R_{g}$	f = 1 MHz		6.5		Ω
Turn-On Delay Time	t <sub>d(on)</sub>			20		
Rise Time	t <sub>r</sub>	$V_{DD} = -15 \text{ V}, I_D = -3 \text{ A},$		14		- ns
Turn-Off Delay Time	t <sub>d(off)</sub>	VGS = - 10 V, Rg = 3 $\Omega$		42		
Fall Time	t <sub>f</sub>	1		5.5		
<b>Drain-Source Body Diode Characteristics</b>			•	•		
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 7	Α
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 28	^
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = - 1 A			- 1.2	V
Body Diode Reverse Recovery Time		L = 2 A di/dt = 100 A/up T = 25 °C		25		ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	$I_F = -3 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s, T}_J = 25 ^{\circ}\text{C}$		59		nC

### Notes:

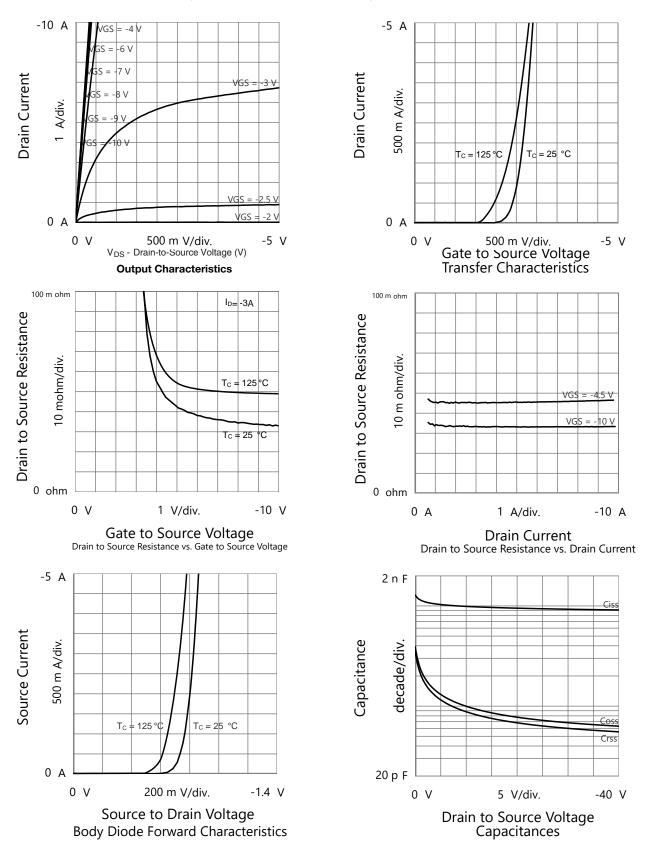
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

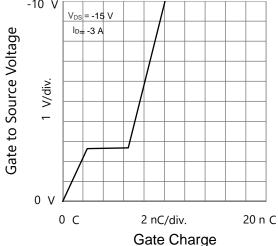
b. Guaranteed by design, not subject to production testing.



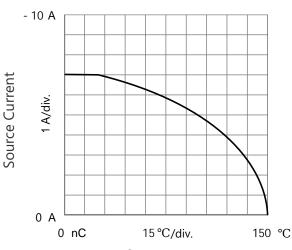
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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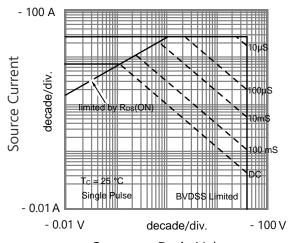


Gate Charge
Gate to Source Voltage vs. GateCharge

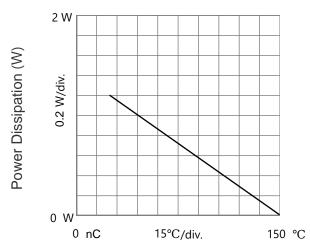


T<sub>C</sub> - Case Temperature

Current Derating

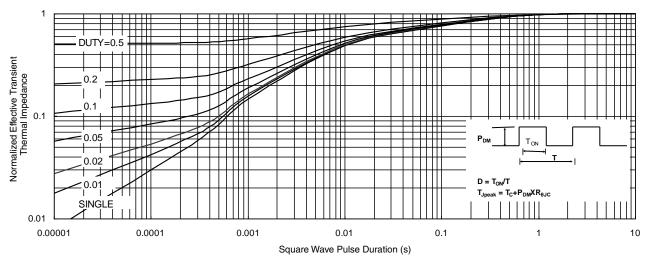


Source to Drain Voltage Safe Operating Area, Junction-to-Ambient



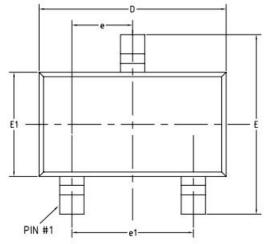
T<sub>C</sub> - Case Temperature

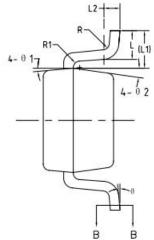
Current Derating

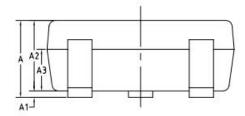


Normalized Thermal Transient Impedance, Junction-to-Case

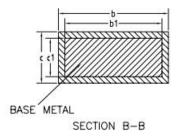
### SOT-23-3L PACKAGE OUTLINE







### **COMMON DIMENSIONS** (UNITS OF MEASURE=MILLIMETER)



SYMBOL	MIN	TYP	MAX
Α	-	-	1.50
A1	0.00	-	0.18
A2	0.85	1.10	1.35
A3	0.58	0.65	0.72
b	0.23	-	0.53
b1	0.20	0.40	0.50
С	0.09	-	0.22
c1	0.08	0.13	0.21
D	2.78	2.95	3.10
Е	2.58	2.80	3.03
E1	1.55	1.65	1.78
е	0.83	0.95	1.07
e1	1.78	1.90	2.02
L	0.28	0.45	0.62
L1	0.59REF		
L2	0.25BSC		
R	0.04	-	-
R1	0.04	-	0.21
θ	0°		8°
θ1	8°	10°	12°
θ2	8°	10°	12°

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